SN74LV374A-EP OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

SCLS500A - MAY 2003 - REVISED MAY 2004

- Controlled Baseline
 One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -40°C to 105°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Supports Mixed-Mode Voltage Operation on All Ports

[†] Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

description/ordering information

The SN74LV374A is an octal edge-triggered D-type flip-flop designed for 2-V to 5.5-V V_{CC} operation.

This device features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

OE does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

TA	PACK	AGE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING							
-40°C to 105°C	TSSOP – PW	SN74LV374ATPWREP	LV374AEP								

ORDERING INFORMATION

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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- I_{off} Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
 2000-V Human-Body Model (A114-A)
 - 2000-V Human-Body Model (A114-A) - 200-V Machine Model (A115-A)
 - 200-V Machine Model (A113-A)
 1000-V Charged-Device Model (C101)

P		PACK		_
OE [1	υ	20] v _{cc}
1Q [2		19] 8Q
1D [3		18] 8D
2D [4		17] 7D
2Q [5		16] 7Q
3Q [6		15] 6Q
3D [7		14	6D
4D [8		13] 5D
4Q [9		12] 5Q
GND [10		11	Сгк

SN74LV374A-EP OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS SCLS500A - MAY 2003 - REVISED MAY 2004

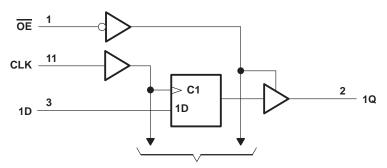
description/ordering information (continued)

To ensure the high-impedance state during power up or power down, OE should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

_	FUNCTION TABLE (each flip-flop)											
	INPUTS OUT											
OE	CLK	Q										
L	\uparrow	Н	Н									
L	\uparrow	L	L									
L	L	Х	Q ₀									
Н	Х	Х	z									

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}
Voltage range applied to any output in the high-impedance or
power-off state, V _O (see Note 1)
Output voltage range, V _O (see Notes 1 and 2)Output voltage range, V _O (see Notes 1 and 2)
Input clamp current, I _{IK} (V _I < 0)
Output clamp current, I _{OK} (V _O < 0)
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$ ±35 mA
Continuous current through V _{CC} or GND ±70 mA
Package thermal impedance, θ_{JA} (see Note 3)
Storage temperature range, T _{stg}
Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



SN74LV374A-EP **OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP** WITH 3-STATE OUTPUTS SCLS500A - MAY 2003 - REVISED MAY 2004

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
VCC	Supply voltage		2	5.5	V
		$V_{CC} = 2 V$	1.5		
	1 Pake Issuel Para di salta na	V_{CC} = 2.3 V to 2.7 V	$V_{CC} \times 0.7$		
VIH	High-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$	$V_{CC} \times 0.7$		V
		V_{CC} = 4.5 V to 5.5 V	$V_{CC} \times 0.7$		
		$V_{CC} = 2 V$		0.5	
.,		V _{CC} = 2.3 V to 2.7 V		$V_{CC} \times 0.3$.,
VIL	Low-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$		$V_{CC} \times 0.3$	V
		V_{CC} = 4.5 V to 5.5 V		$V_{CC} \times 0.3$	
VI	Input voltage		0	5.5	V
		High or low state	0	VCC	
VO	Output voltage	3-state	0	5.5	V
		V _{CC} = 2 V		-50	μA
		V _{CC} = 2.3 V to 2.7 V		-2	
ЮН	High-level output current	V _{CC} = 3 V to 3.6 V		-8	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-16	
		$V_{CC} = 2 V$		50	μA
		V_{CC} = 2.3 V to 2.7 V		2	
IOL	Low-level output current	V _{CC} = 3 V to 3.6 V		8	mA
		V _{CC} = 4.5 V to 5.5 V		16	
		V _{CC} = 2.3 V to 2.7 V		200	
Δt/Δv	Input transition rise or fall rate	V _{CC} = 3 V to 3.6 V		100	ns/V
		V _{CC} = 4.5 V to 5.5 V		20	
TA	Operating free-air temperature	<u>.</u>	-40	105	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	UNIT
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1			
	$I_{OH} = -2 \text{ mA}$	2.3 V	2			
VOH	$I_{OH} = -8 \text{ mA}$	3 V	2.48			V
	I _{OH} = -16 mA	4.5 V	3.8			
	I _{OL} = 50 μA	2 V to 5.5 V			0.1	
	I _{OL} = 2 mA	2.3 V			0.4	.,
VOL	I _{OL} = 8 mA	3 V			0.44	V
	I _{OL} = 16 mA	4.5 V			0.55	
lj	V _I = 5.5 V or GND	0 to 5.5 V			±1	μΑ
I _{OZ}	$V_{O} = V_{CC}$ or GND	5.5 V			±5	μΑ
ICC	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			20	μΑ
loff	V_{I} or $V_{O} = 0$ to 5.5 V	0			5	μΑ
Ci	$V_I = V_{CC}$ or GND	3.3 V		2.9		pF



SN74LV374A-EP **OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP** WITH 3-STATE OUTPUTS

SCLS500A - MAY 2003 - REVISED MAY 2004

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

		T _A = 2	25°C			
		MIN	MAX	MIN	MAX	UNIT
tw	Pulse duration, CLK high or low	5		5.5		ns
t _{su}	Setup time, data before CLK↑	4.5		4.5		ns
t _h	Hold time, data after CLK↑	2		2		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

		T _A = 2	25°C			
		MIN	MAX	MIN	MAX	UNIT
tw	Pulse duration, CLK high or low	5		5		ns
t _{su}	Setup time, data before CLK↑	3		3		ns
th	Hold time, data after CLK↑	2		2		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T,	₄ = 25°C	;			
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
f _{max}				55	110		50		MHz
^t pd	CLK	Q			8.3	16.2	1	18.5	
t _{en}	OE	Q	C _L = 50 pF		7.7	14.5	1	17.5	
^t dis	OE	Q			5.9	14	1	16	ns
^t sk(o)						1.5			

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	Т	₄ = 25°C	;			
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
f _{max}				85	170		75		MHz
^t pd	CLK	Q			5.9	10.1	1	13.5	
t _{en}	OE	Q	C _L = 50 pF		5.5	9.6	1	13	
^t dis	OE	Q]		4	8.8	1	10	ns
^t sk(o)						1			



SN74LV374A-EP **OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP** WITH 3-STATE OUTPUTS SCLS500A - MAY 2003 - REVISED MAY 2004

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 5)

	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.6	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.5	-0.8	V
VOH(V)	Quiet output, minimum dynamic V _{OH}		2.9		V
VIH(D)	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.

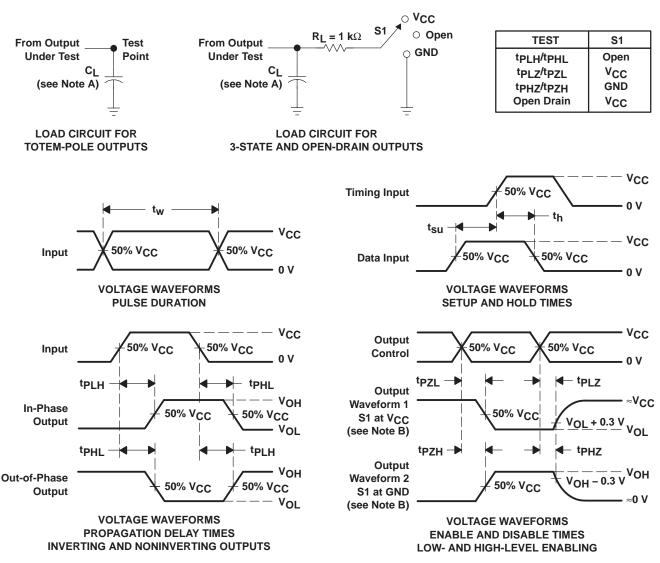
operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER		TEST CO	V _{CC}	TYP	UNIT	
	Dower dissinction conscitutes		C. 50 mF	f = 10 MHz	3.3 V	21.1	۶F
Cpd	Power dissipation capacitance	Outputs enabled	C _L = 50 pF,		5 V	22.8	рг



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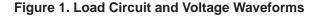
SCLS500A - MAY 2003 - REVISED MAY 2004



PARAMETER MEASUREMENT INFORMATION

NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \le 1$ MHz, $Z_{O} = 50 \Omega$, $t_{f} \le 3$ ns, $t_{f} \le 3$ ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. t_{PI7} and t_{PH7} are the same as t_{dis} .
- F. t_{P71} and t_{P7H} are the same as t_{en} .
- G. t_{PLL} and t_{PLH} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins P	ackage Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV374ATPWREP	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03663-01XE	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LV374A-EP :

- Catalog: SN74LV374A
- Automotive: SN74LV374A-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

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